

PATENT

Claim Amendments:

Please amend the claims as follows:

1. (Withdrawn)
2. (Withdrawn)
3. (Withdrawn)
4. (Withdrawn)
5. (Withdrawn)
6. (Withdrawn)
7. (Withdrawn)
8. (Withdrawn)
9. (Withdrawn)
10. (Withdrawn)
11. Withdrawn)
12. (Withdrawn)
13. (Withdrawn)

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end*
14. (Original) An apparatus comprising:
semiconductor substrate having an input output (IO) ring, the IO ring having a bond pad portion and an active buffer portion;
the bond pad portion including:
a first bond pad;
a second set of bond pads having one or more bond pads;
a third bond pad, wherein the second set of bond pads is immediately adjacent to the first and third bond pads; and
a conductive trace coupling the first bond pad to the third bond pad.
15. (Original) The apparatus of claim 14, wherein the first bond pad and the third bond pad are power pads, wherein a power pad is to be coupled to a fixed voltage source.
16. (Original) The apparatus of claim 15, wherein the fixed voltage source is one of Vdd and Vss.
17. (Original) The apparatus of claim 14, further comprising:
a package substrate having a power portion, wherein the power portion is to provide a fixed voltage;
a first bond wire connected to the first bond pad and the power portion;
a second bond wire connected to the third bond pad and the power portion.
18. (Original) The apparatus of claim 17 further comprising exactly one of the first bond pad and the third bond pad being connected to the active buffer portion of the IO ring.
19. (Original) The apparatus of claim 14, wherein the second set of bond pads includes one bond pad.
20. (Original) The apparatus of claim 14, wherein the second set of bond pads includes more than one bond pads.